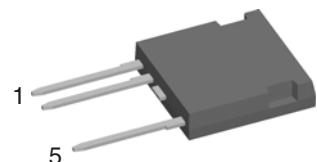
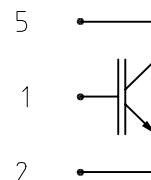


**High Voltage
BIMOSFET™
in High Voltage ISOPLUS i4-PAC™**

Monolithic Bipolar MOS Transistor

I_{C25} = 7 A
 V_{CES} = 1600 V
 $V_{CE(sat)}$ = 4.9 V
 t_f = 70 ans



IGBT

Symbol	Conditions	Maximum Ratings		
V_{CES}	$T_{VJ} = 25^\circ\text{C}$ to 150°C	1600	V	
V_{GES}		± 20	V	
I_{C25}	$T_c = 25^\circ\text{C}$	7	A	
I_{C90}	$T_c = 90^\circ\text{C}$	4	A	
I_{CM}	$V_{GE} = 10/0 \text{ V}; R_G = 27 \Omega; T_{VJ} = 125^\circ\text{C}$	12	A	
V_{CEK}	RBSOA, Clamped inductive load; $L = 100 \mu\text{H}$	$0.8 \cdot V_{CES}$		
P_{tot}	$T_c = 25^\circ\text{C}$	70	W	

Symbol	Conditions	Characteristic Values		
		($T_{VJ} = 25^\circ\text{C}$, unless otherwise specified)		
		min.	typ.	max.
$V_{CE(sat)}$	$I_C = 5 \text{ A}; V_{GE} = 15 \text{ V}; T_{VJ} = 25^\circ\text{C}$ $T_{VJ} = 125^\circ\text{C}$	4.9 5.6	7 V	V
$V_{GE(th)}$	$I_C = 0.5 \text{ mA}; V_{GE} = V_{CE}$	3.5		5.5 V
I_{CES}	$V_{CE} = 0.8V_{CES}; V_{GE} = 0 \text{ V}; T_{VJ} = 25^\circ\text{C}$ $T_{VJ} = 125^\circ\text{C}$		0.1 mA	mA
I_{GES}	$V_{CE} = 0 \text{ V}; V_{GE} = \pm 20 \text{ V}$		500 nA	nA
$t_{d(on)}$ t_r $t_{d(off)}$ t_f	Inductive load, $T_{VJ} = 125^\circ\text{C}$ $V_{CE} = 960 \text{ V}; I_C = 5 \text{ A}$ $V_{GE} = 10/0 \text{ V}; R_G = 27 \Omega$	140 200 120 70		ns ns ns ns
C_{ies} Q_{Gon}	$V_{CE} = 25 \text{ V}; V_{GE} = 0 \text{ V}; f = 1 \text{ MHz}$ $V_{CE} = 600 \text{ V}; V_{GE} = 10 \text{ V}; I_C = 5 \text{ A}$	550 34		pF nC
V_F	(reverse conduction); $I_F = 5 \text{ A}$	3.6		V
R_{thJC}			1.75	K/W

Features

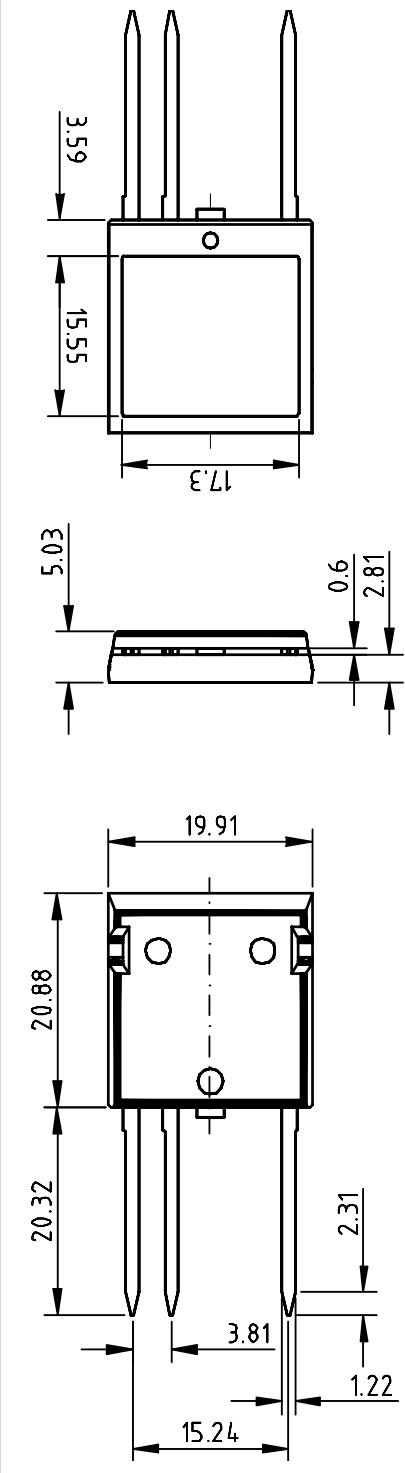
- High Voltage BIMOSFET™
 - substitute for high voltage MOSFETs with significantly lower voltage drop
 - MOSFET compatible control 10 V turn on gate voltage
 - fast switching for high frequency operation
 - reverse conduction capability
- ISOPLUS i4-PAC™
 - high voltage package
 - isolated back surface
 - enlarged creepage towards heatsink
 - enlarged creepage between high voltage pins
 - application friendly pinout
 - high reliability
 - industry standard outline

Applications

- switched mode power supplies
- DC-DC converters
- resonant converters
- lamp ballasts
- laser generators, x ray generators

Component

Symbol	Conditions	Maximum Ratings		
		-55...+150	+125	°C
T_{VJ}		-55...+125		°C
T_{stg}				°C
V_{ISOL}	$I_{ISOL} \leq 1 \text{ mA}; 50/60 \text{ Hz}$	2500	V~	
F_c	mounting force with clip	20...120	N	
Symbol	Conditions	Characteristic Values		
		min.	typ.	max.
$d_s d_A$	pin 2 - pin 5	7		mm
$d_s d_A$	pin - backside metal	5.5		mm
R_{thCH}	with heatsink compound	0.15		K/W
Weight		9		g

Dimensions in mm (1 mm = 0.0394")

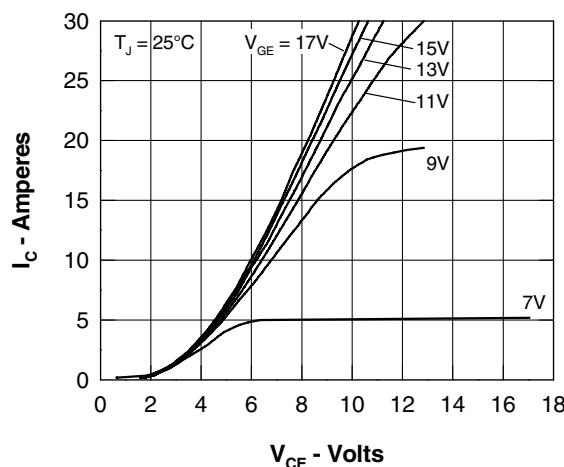


Fig. 1 Typ. Output Characteristics

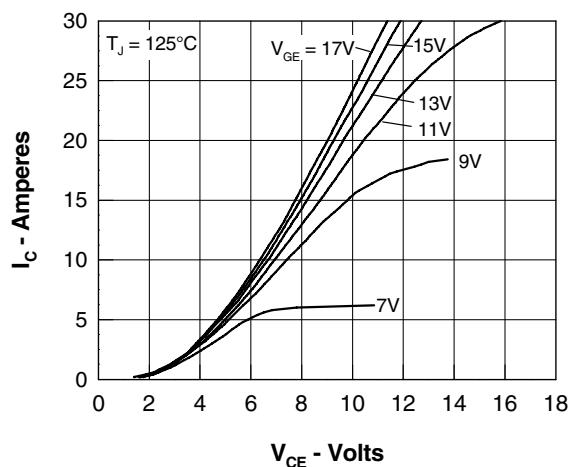


Fig. 2 Typ. Output Characteristics

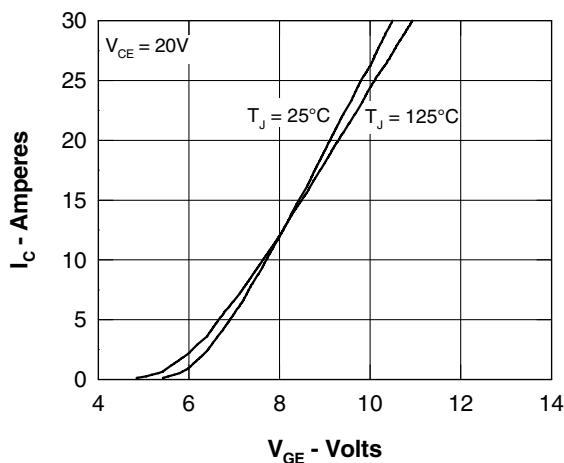


Fig. 3 Typ. Transfer Characteristics

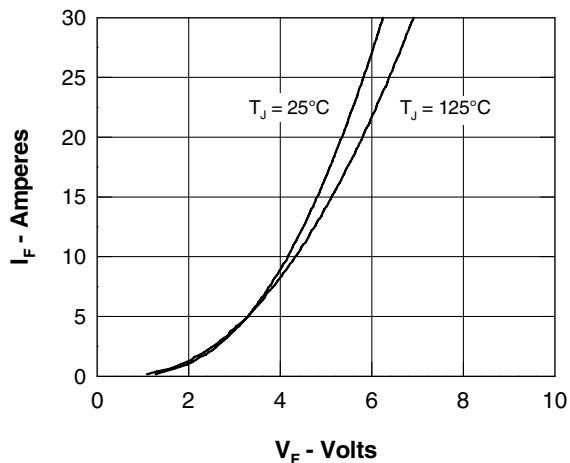


Fig. 4 Typ. Characteristics of Reverse Conduction

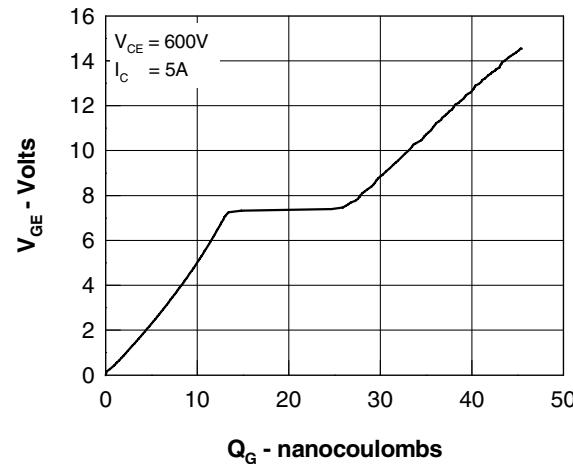


Fig. 5 Typ. Gate Charge characteristics

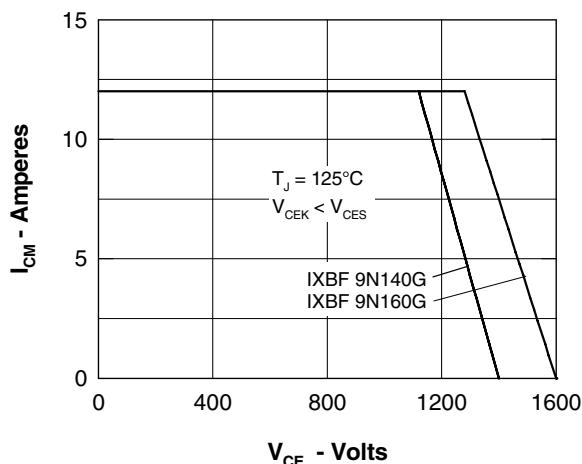


Fig. 6 Reverse Biased Safe Operating Area RBSOA

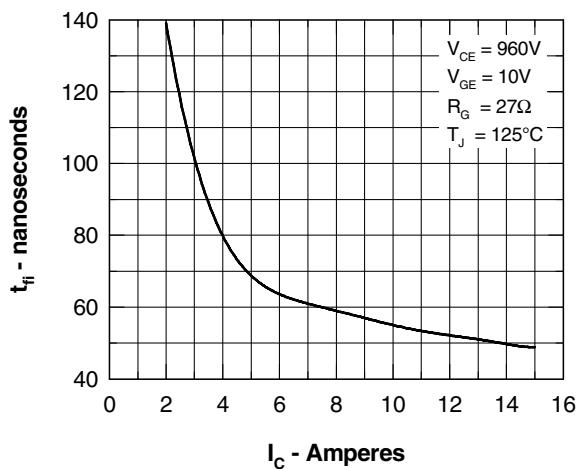


Fig. 7 Typ. Fall Time

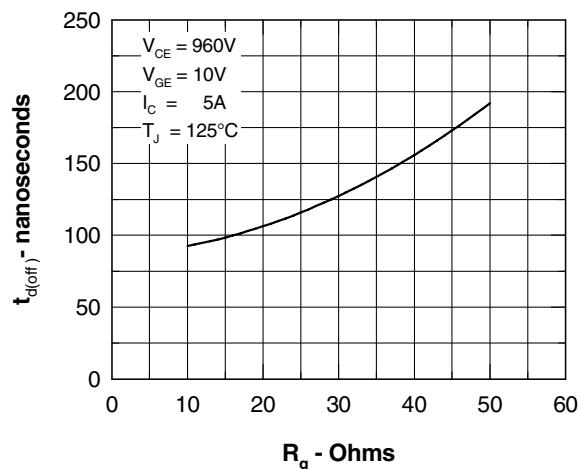


Fig. 8 Typ. Turn Off Delay Time

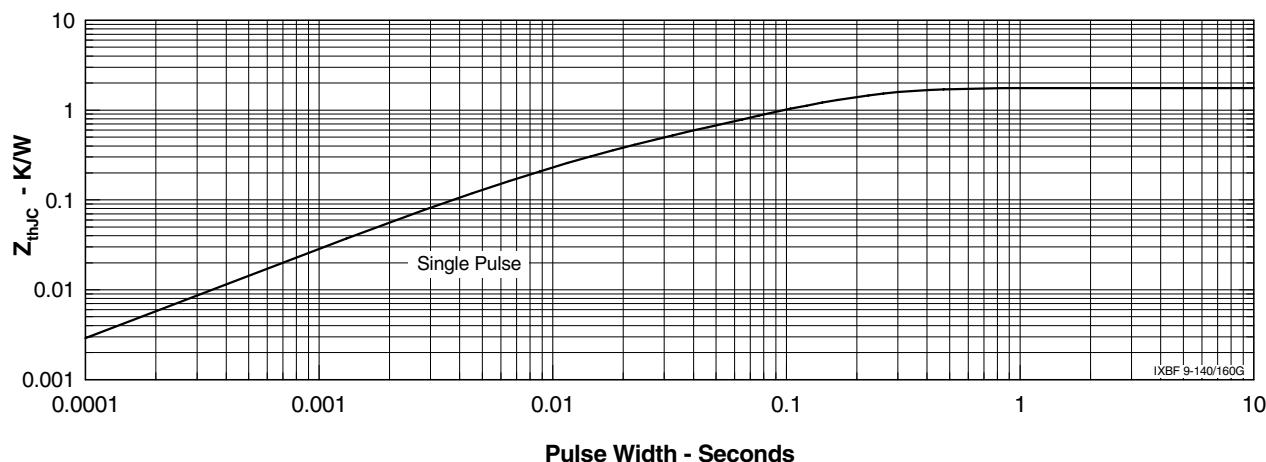


Fig. 9 Typ. Transient Thermal Impedance



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